

WHAT IS CLAIMED IS:

1. A wafer processing method of dividing a wafer along a plurality of crossing division lines to obtain a plurality of individual devices and mounting an adhesive film for die bonding on a back side of each device, said division lines being formed on a front side of said wafer to thereby define a plurality of separate regions where said respective devices are formed, said wafer processing method comprising:

a wafer supporting step of mounting one side of said adhesive film on a back side of said wafer and attaching an other side of said adhesive film to a dicing tape composed of a base sheet and an ultraviolet curable adhesive layer formed on said base sheet, said adhesive film being attached to said ultraviolet curable adhesive layer of said dicing tape;

an ultraviolet light applying step of applying ultraviolet light to said dicing tape to thereby cure said adhesive layer after performing said wafer supporting step; and

a cutting step of rotating a cutting blade having a peripheral cutting edge to cut said wafer together with said adhesive film along said division lines after performing said ultraviolet light applying step, thereby dividing said wafer into said individual devices;

said cutting edge of said cutting blade being positioned so that said cutting edge cuts partially into said cured adhesive layer in said cutting step.